IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

n re Application of:)
Yeo et al.)
Serial No.:	Express Mail Certification
Filed :	Label No. EV016784297US
For: ENHANCED CHIP SCALE PACKAGE FOR FLIP CHIPS)))
Attorney's Docket No.: 4795-001)
	Raleigh, North Carolina February 19, 2002

Commissioner for Patents BOX PATENT APPLICATION Washington, D.C. 20231

Dear Sir:

CLAIM OF PRIORITY

The applicant in this case claims priority based on a prior application filed in Singapore and identified as Singapore Patent Application No. 200106785-9 filed on November 2, 2001.

A certified copy of the Singapore application will be submitted in due course.

Respectfully submitted,

COATS & BENNETT, P.L.L.C.

By:

Registration No. 25,620

Telephone: (919) 854-1844